

MC14512B

8-Channel Data Selector

The MC14512B is an 8-channel data selector constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. This data selector finds primary application in signal multiplexing functions. It may also be used for data routing, digital signal switching, signal gating, and number sequence generation.

Features

- Diode Protection on All Inputs
- Single Supply Operation
- 3-State Output (Logic “1”, Logic “0”, High Impedance)
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range
- Pb-Free Packages are Available*

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Parameter	Symbol	Value	Unit
DC Supply Voltage Range	V_{DD}	-0.5 to +18.0	V
Input or Output Voltage Range (DC or Transient)	V_{in}, V_{out}	-0.5 to V_{DD} + 0.5	V
Input or Output Current (DC or Transient) per Pin	I_{in}, I_{out}	± 10	mA
Power Dissipation, Per Package (Note 1)	P_D	500	mW
Ambient Temperature Range	T_A	-55 to +125	$^{\circ}C$
Storage Temperature Range	T_{stg}	-65 to +150	$^{\circ}C$
Lead Temperature (8-Second Soldering)	T_L	260	$^{\circ}C$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating: Plastic “P and D/DW”

Packages: - 7.0 mW/ $^{\circ}C$ From 65 $^{\circ}C$ To 125 $^{\circ}C$

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

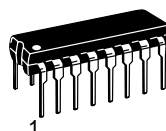
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



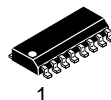
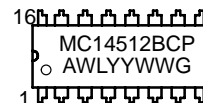
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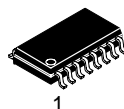
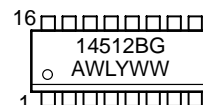
MARKING DIAGRAMS



PDIIP-16
P SUFFIX
CASE 648



SOIC-16
D SUFFIX
CASE 751B



SOEIAJ-16
F SUFFIX
CASE 966



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

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TRUTH TABLE

C	B	A	Inhibit	Disable	Z
0	0	0	0	0	X0
0	0	1	0	0	X1
0	1	0	0	0	X2
0	1	1	0	0	X3
1	0	0	0	0	X4
1	0	1	0	0	X5
1	1	0	0	0	X6
1	1	1	0	0	X7
X	X	X	1	0	0
X	X	X	X	1	High Impedance

NOTE: X = Don't Care

PIN ASSIGNMENT

X0	1 ●	16	V _{DD}
X1	2	15	DIS
X2	3	14	Z
X3	4	13	C
X4	5	12	B
X5	6	11	A
X6	7	10	INH
V _{SS}	8	9	X7

ORDERING INFORMATION

Device	Package	Shipping†
MC14512BCP	PDIP-16	25 Units / Rail
MC14512BCPG	PDIP-16 (Pb-Free)	
MC14512BD	SOIC-16	48 Units / Rail
MC14512BDG	SOIC-16 (Pb-Free)	
MC14512BDR2	SOIC-16	2500 / Tape & Reel
MC14512BDR2G	SOIC-16 (Pb-Free)	
MC14512BF	SOEIAJ-16	50 Units / Rail
MC14512BFG	SOEIAJ-16 (Pb-Free)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V_{DD} Vdc	-55°C		25°C			125°C		Unit	
			Min	Max	Min	Typ (Note 2)	Max	Min	Max		
Output Voltage $V_{in} = V_{DD}$ or 0	V_{OL}	5.0	–	0.05	–	0	0.05	–	0.05	Vdc	
		10	–	0.05	–	0	0.05	–	0.05		
$V_{in} = 0$ or V_{DD}	V_{OH}	5.0	4.95	–	4.95	5.0	–	4.95	–	Vdc	
		10	9.95	–	9.95	10	–	9.95	–		
Input Voltage ($V_O = 4.5$ or 0.5 Vdc) ($V_O = 9.0$ or 1.0 Vdc) ($V_O = 13.5$ or 1.5 Vdc)	V_{IL}	5.0	–	1.5	–	2.25	1.5	–	1.5	Vdc	
		10	–	3.0	–	4.50	3.0	–	3.0		
($V_O = 0.5$ or 4.5 Vdc) ($V_O = 1.0$ or 9.0 Vdc) ($V_O = 1.5$ or 13.5 Vdc)	V_{IH}	5.0	3.5	–	3.5	2.75	–	3.5	–	Vdc	
		10	7.0	–	7.0	5.50	–	7.0	–		
Output Drive Current ($V_{OH} = 2.5$ Vdc) ($V_{OH} = 4.6$ Vdc) ($V_{OH} = 9.5$ Vdc) ($V_{OH} = 13.5$ Vdc)	Source	5.0	–3.0	–	–2.4	–4.2	–	–1.7	–	mA c	
		5.0	–0.64	–	–0.51	–0.88	–	–0.36	–		
($V_{OL} = 0.4$ Vdc) ($V_{OL} = 0.5$ Vdc) ($V_{OL} = 1.5$ Vdc)	Sink	10	–1.6	–	–1.3	–2.25	–	–0.9	–	mA c	
		15	–4.2	–	–3.4	–8.8	–	–2.4	–		
Input Current	I_{in}	15	–	± 0.1	–	± 0.00001	± 0.1	–	± 1.0	μ Adc	
Input Capacitance ($V_{in} = 0$)	C_{in}	–	–	–	–	5.0	7.5	–	–	pF	
Quiescent Current (Per Package)	I_{DD}	5.0	–	5.0	–	0.005	5.0	–	150	μ Adc	
		10	–	10	–	0.010	10	–	300		
		15	–	20	–	0.015	20	–	600		
Total Supply Current (Note 3) (Note 4) (Dynamic plus Quiescent, Per Package) ($C_L = 50$ pF on all outputs, all buffers switching)	I_T	5.0	$I_T = (0.8 \mu\text{A}/\text{kHz}) f + I_{DD}$								μ Adc
		10	$I_T = (1.6 \mu\text{A}/\text{kHz}) f + I_{DD}$								
		15	$I_T = (2.4 \mu\text{A}/\text{kHz}) f + I_{DD}$								
3–State Leakage Current	I_{TL}	15	–	± 0.1	–	± 0.0001	± 0.1	–	± 3.0	μ Adc	

2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

3. The formulas given are for the typical characteristics only at 25°C.

4. To calculate total supply current at loads other than 50 pF: $I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$ where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and $k = 0.001$.

SWITCHING CHARACTERISTICS (Note 5) ($C_L = 50$ pF, $T_A = 25^\circ\text{C}$, See Figure 1)

Characteristic	Symbol	V_{DD}	All Types		Unit
			Typ (Note 6)	Max	
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	t_{TLH}, t_{THL}	5.0	100	200	ns
		10	50	100	
		15	40	80	
Propagation Delay Time (Figure 2) Inhibit, Control, or Data to Z	t_{PLH}	5.0	330	650	ns
		10	125	250	
		15	85	170	
Propagation Delay Time (Figure 2) Inhibit, Control, or Data to Z	t_{PHL}	5.0	330	650	ns
		10	125	250	
		15	85	170	
3–State Output Delay Times (Figure 3) "1" or "0" to High Z, and High Z to "1" or "0"	$t_{PHZ}, t_{PLZ}, t_{PZH}, t_{PZL}$	5.0	60	150	ns
		10	35	100	
		15	30	75	

5. The formulas given are for the typical characteristics only at 25°C.

6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

MC14512B

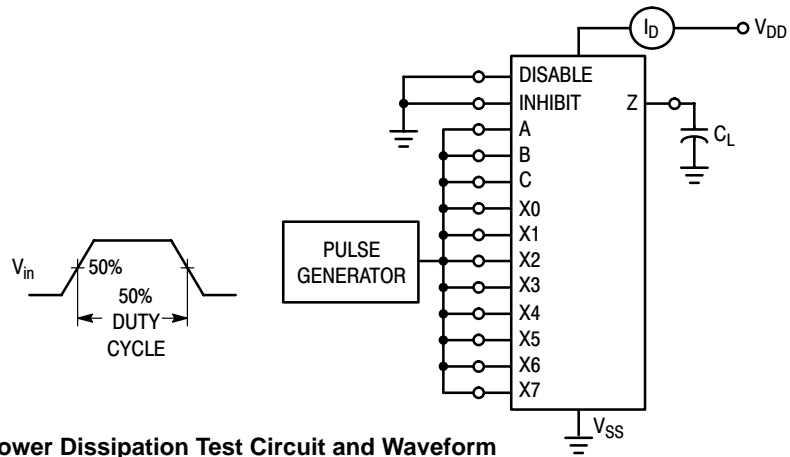


Figure 1. Power Dissipation Test Circuit and Waveform

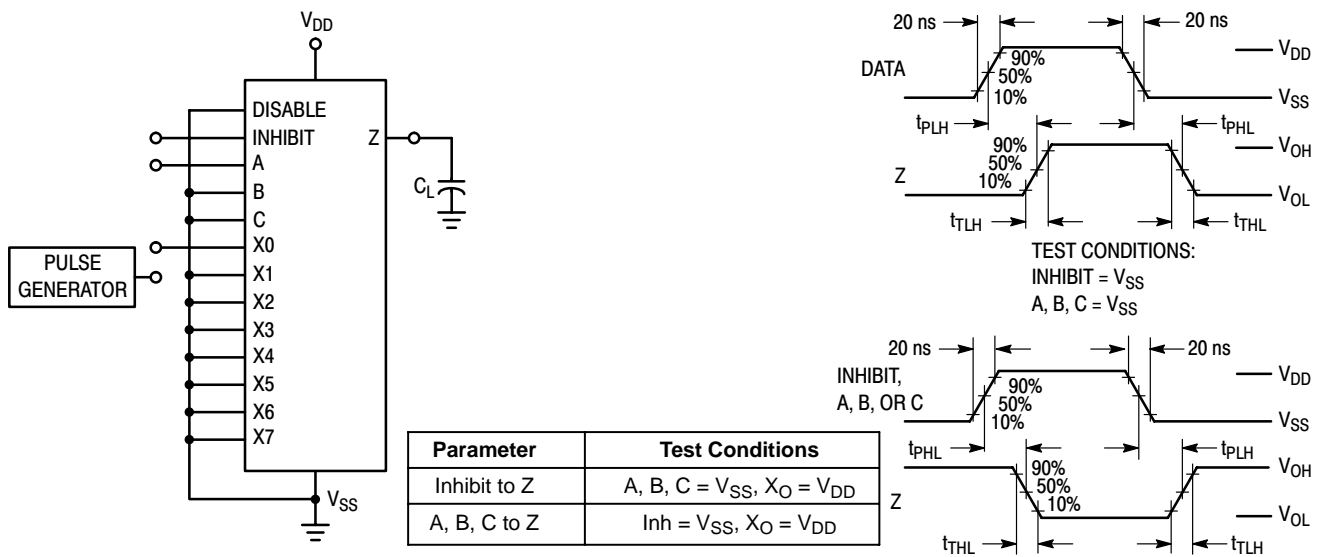


Figure 2. AC Test Circuit and Waveforms

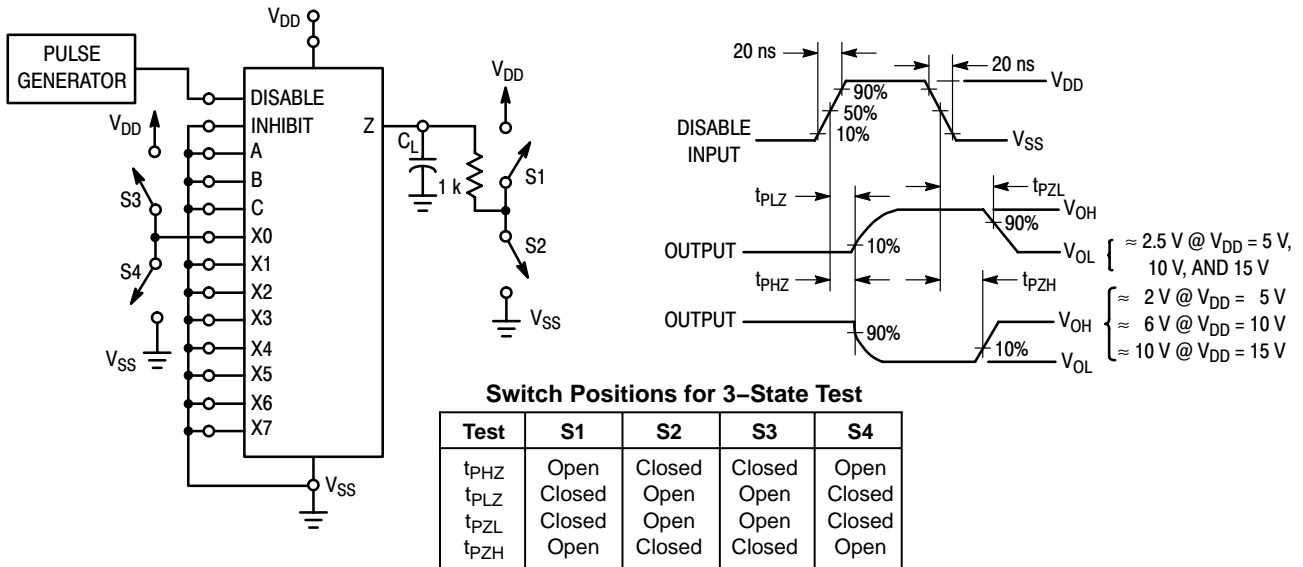
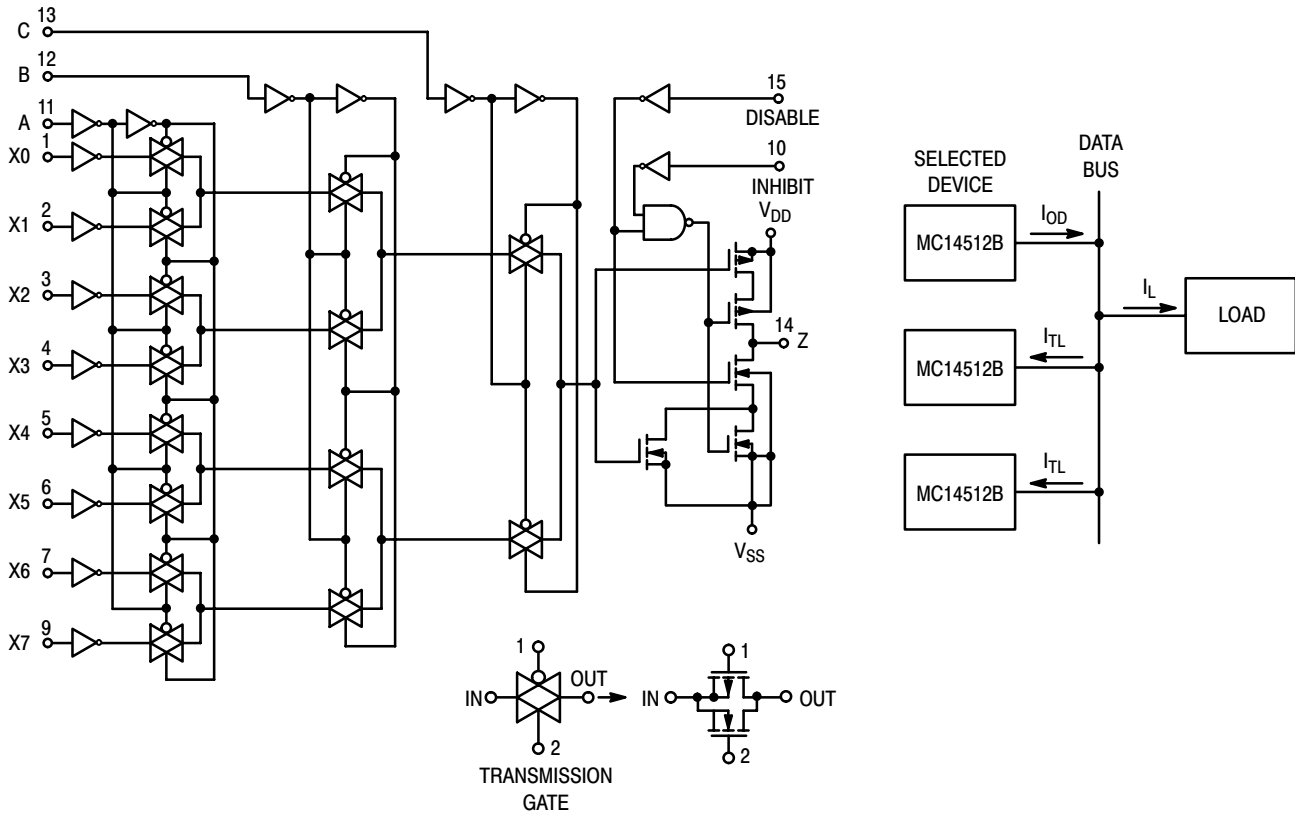


Figure 3. 3-State AC Test Circuit and Waveform

MC14512B

LOGIC DIAGRAM



3-STATE MODE OF OPERATION

Output terminals of several MC14512B 8-Bit Data Selectors can be connected to a single data bus as shown. One MC14512B is selected by the 3-state control, and the remaining devices are disabled into a high-impedance "off" state. The number of 8-bit data selectors, N , that may be connected to a bus line is determined from the output drive current, I_{OD} , 3-state or disable output leakage current, I_{TL} , and the load current, I_L , required to drive the bus line

(including fanout to other device inputs), and can be calculated by:

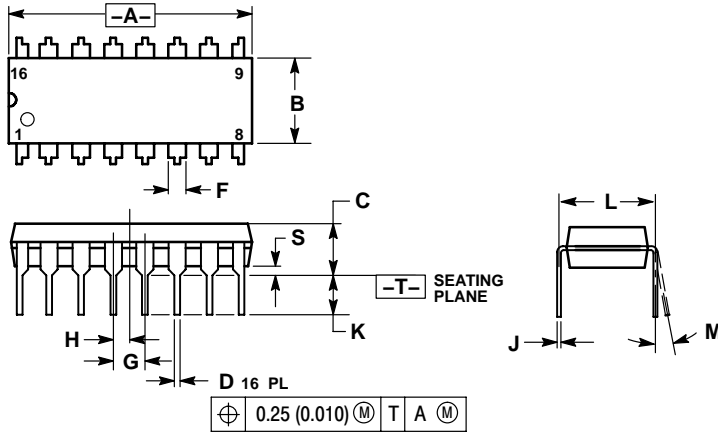
$$N = \frac{I_{OD} - I_L}{I_{TL}} + 1$$

N must be calculated for both high and low logic state of the bus line.

MC14512B

PACKAGE DIMENSIONS

PDIP-16
CASE 648-08
ISSUE T

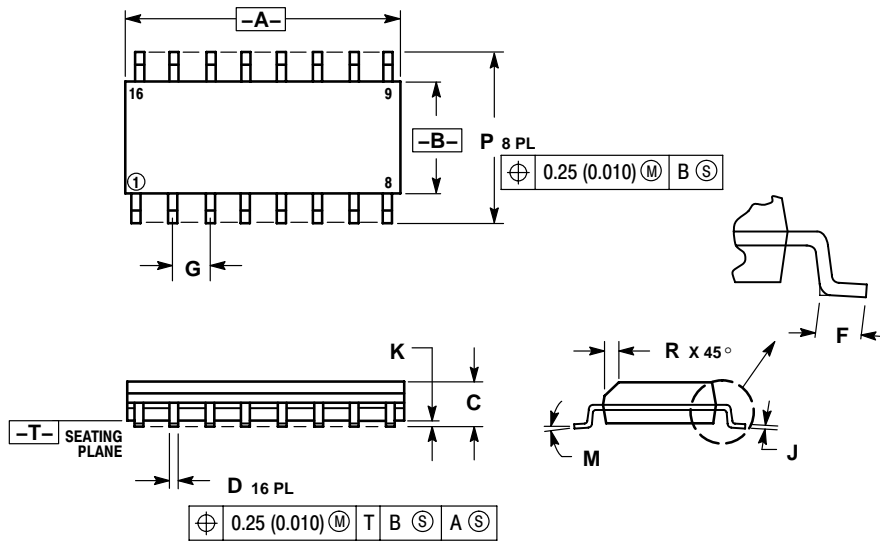


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

SOIC-16
CASE 751B-05
ISSUE J



NOTES:

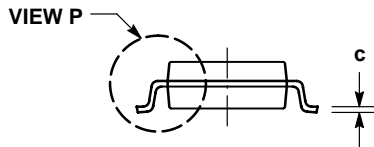
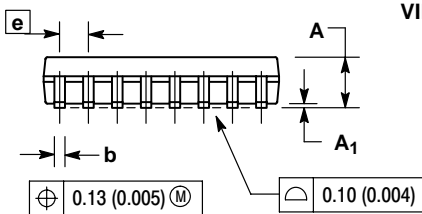
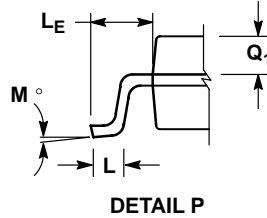
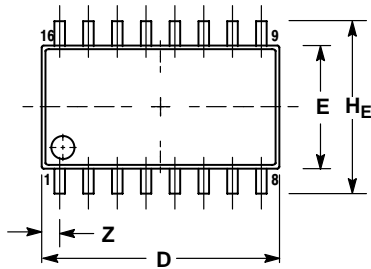
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

MC14512B

PACKAGE DIMENSIONS

SOEIAJ-16
CASE 966-01
ISSUE A



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H _E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L _E	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q ₁	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

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